

FEATURES

- **Wide Bandwidth**
(BW = 900 MHz Typ, 1.8 Gbps)
- **Low Crosstalk** ($X_{\text{TALK}} = -41$ dB Typ)
- **Low Bit-to-Bit Skew** ($t_{\text{sk(o)}} = 0.2$ ns Max)
- **Low and Flat ON-State Resistance**
($r_{\text{on}} = 4 \Omega$ Typ, $r_{\text{on(flat)}} = 0.7 \Omega$ Typ)
- **Low Input/Output Capacitance**
($C_{\text{ON}} = 10$ pF Typ)
- **Rail-to-Rail Switching on Data I/O Ports**
(0 to 5 V)
- **V_{DD} Operating Range From 3 V to 3.6 V**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Performance Tested Per JESD 22**
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)
- **Applications**
 - Digital Video Signal Switching
 - Differential DVI, HDMI Signal Muxing for Audio/Video Receivers and High Definition Television (HDTV)

**DGG OR DGV PACKAGE
(TOP VIEW)**

V _{DD}	1	48	0B ₁
A ₀	2	47	1B ₁
GND	3	46	GND
A ₁	4	45	0B ₂
GND	5	44	1B ₂
V _{DD}	6	43	GND
GND	7	42	2B ₁
A ₂	8	41	3B ₁
GND	9	40	GND
A ₃	10	39	2B ₂
GND	11	38	3B ₂
V _{DD}	12	37	GND
GND	13	36	V _{DD}
NC	14	35	4B ₁
A ₄	15	34	5B ₁
GND	16	33	GND
A ₅	17	32	4B ₂
GND	18	31	5B ₂
V _{DD}	19	30	GND
GND	20	29	6B ₁
A ₆	21	28	7B ₁
GND	22	27	GND
A ₇	23	26	6B ₂
SEL	24	25	7B ₂

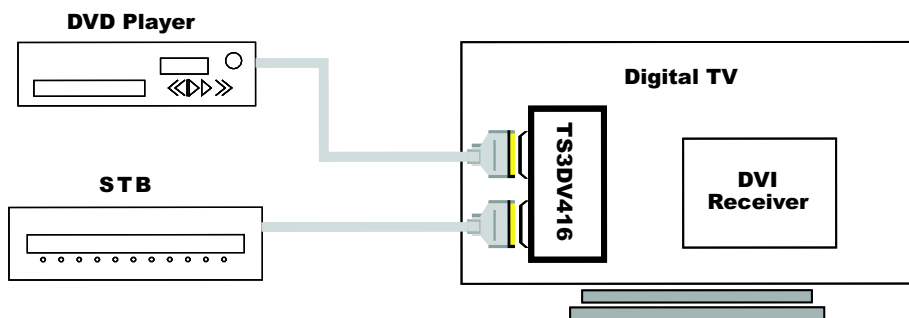
NC – No internal connection

DESCRIPTION/ORDERING INFORMATION

The TS3DV416 is a 16-bit to 8-bit multiplexer/demultiplexer digital video switch with a single select (SEL) input. SEL controls the data path of the multiplexer/demultiplexer.

The device provides a low and flat on-state resistance (r_{on}) and an excellent on-resistance match. Low input/output capacitance, high-bandwidth, low skew, and low crosstalk among channels make this device suitable for various digital video applications, such as DVI and HDMI.

TYPICAL APPLICATION



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TS3DV416

4-CHANNEL DIFFERENTIAL 8:16 MUX SWITCH

FOR DVI/HDMI APPLICATIONS

SCDS198–OCTOBER 2005

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – DGG	Tape and reel	TS3DV416DGGR	TBD
	TVSOP – DGV	Tape and reel	TS3DV416DGVR	TBD

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

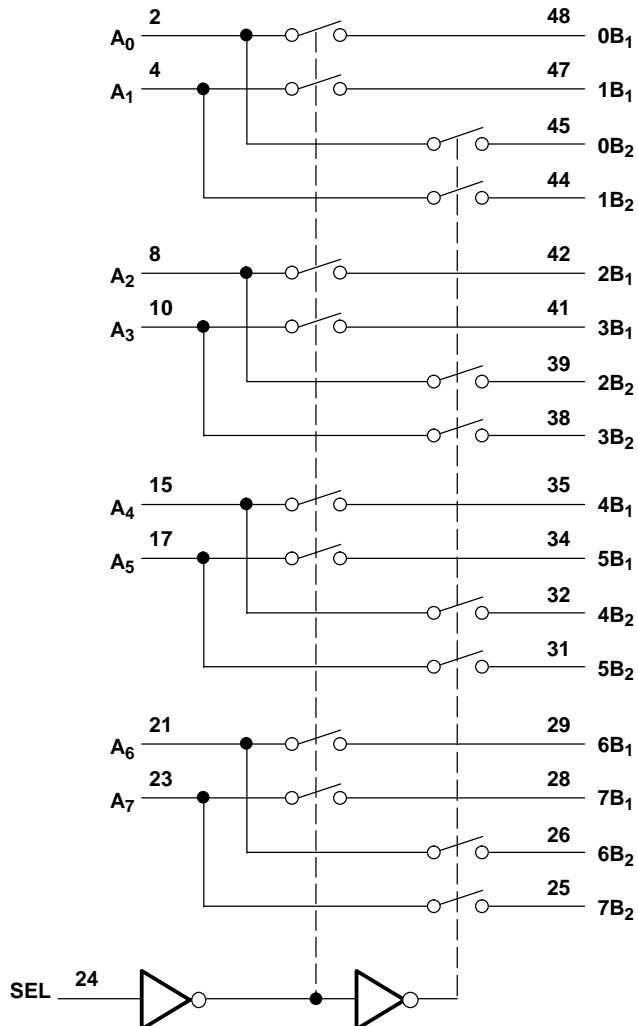
FUNCTION TABLE

INPUT SEL	INPUT/ OUTPUT A_n	FUNCTION	
L	nB_1	$A_n = nB_1$	nB_2 high-impedance mode
H	nB_2	$A_n = nB_2$	nB_1 high-impedance mode

PIN DESCRIPTION

NAME	DESCRIPTION
A_n	Data I/O
nB_m	Data I/O
SEL	Select input

LOGIC DIAGRAM (POSITIVE LOGIC)



TS3DV416

4-CHANNEL DIFFERENTIAL 8:16 MUX SWITCH

FOR DVI/HDMI APPLICATIONS

SCDS198–OCTOBER 2005



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	−0.5	4.6	V
V_{IN}	Control input voltage range ⁽²⁾⁽³⁾	−0.5	7	V
$V_{I/O}$	Switch I/O voltage range ⁽²⁾⁽³⁾⁽⁴⁾	−0.5	7	V
I_{IK}	Control input clamp current	$V_{IN} < 0$		−50 mA
$I_{I/O}$	I/O port clamp current	$V_{I/O} < 0$		−50 mA
$I_{I/O}$	ON-state switch current ⁽⁵⁾	±128		mA
	Continuous current through V_{CC} or GND	±100		mA
θ_{JA}	Package thermal impedance ⁽⁶⁾	DGG package		70 °C/W
		DGV package		58
T_{stg}	Storage temperature range	−65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4) V_I and V_O are used to denote specific conditions for $V_{I/O}$.
- (5) I_I and I_O are used to denote specific conditions for $I_{I/O}$.
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	3	3.6	V
V_{IH}	High-level control input voltage (SEL)	2	5.5	V
V_{IL}	Low-level control input voltage (SEL)	0	0.8	V
$V_{I/O}$	Input/output voltage	0	5.5	V
T_A	Operating free-air temperature	−40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics⁽¹⁾

for high frequency switching over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V_{IK}	SEL	$V_{DD} = 3.6 \text{ V}$, $I_{IN} = -18 \text{ mA}$		-0.7	-1.2	V
I_{IH}	SEL	$V_{DD} = 3.6 \text{ V}$, $V_{IN} = V_{DD}$			± 1	μA
I_{IL}	SEL	$V_{DD} = 3.6 \text{ V}$, $V_{IN} = \text{GND}$			± 1	μA
I_{off}		$V_{DD} = 0$, $V_O = 0 \text{ to } 3.6 \text{ V}$, $V_I = 0$			1	μA
I_{CC}		$V_{DD} = 3.6 \text{ V}$, $I_{IO} = 0$, Switch ON or OFF		250	600	mA
C_{IN}	SEL	$f = 1 \text{ MHz}$, $V_{IN} = 0$		2.5	3	pF
C_{OFF}	B port	$V_I = 0$, $f = 1 \text{ MHz}$, Outputs open, Switch OFF		3.5	4	pF
C_{ON}		$V_I = 0$, $f = 1 \text{ MHz}$, Outputs open, Switch ON		10	10.9	pF
r_{on}		$V_{DD} = 3 \text{ V}$, $1.5 \text{ V} \leq V_I \leq V_{DD}$, $I_O = -40 \text{ mA}$		4	8	Ω
$r_{on(flat)}$ ⁽³⁾		$V_{DD} = 3 \text{ V}$, $V_I = 1.5 \text{ V}$ and V_{DD} , $I_O = -40 \text{ mA}$		0.7		Ω
Δr_{on} ⁽⁴⁾		$V_{CC} = 3 \text{ V}$, $1.5 \text{ V} \leq V_I \leq V_{CC}$, $I_O = -40 \text{ mA}$		0.2	1.2	Ω

- (1) V_I , V_O , I_I , and I_O refer to I/O pins. V_{IN} refers to the control inputs.
(2) All typical values are at $V_{DD} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.
(3) $r_{on(flat)}$ is the difference of r_{on} in a given channel at specified voltages.
(4) Δr_{on} is the difference of r_{on} from center (A_4 , A_5) ports to any other port.

Switching Characteristics

over recommended operating free-air temperature range $V_{DD} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $R_L = 200 \Omega$, $C_L = 10 \text{ pF}$ (unless otherwise noted) (see [Figure 4](#) and [Figure 5](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP ⁽¹⁾	MAX	UNIT
t_{pd} ⁽²⁾	A or B	B or A		0.04		ns
t_{PZH} , t_{PZL}	SEL	A or B	1.5		11.5	ns
t_{PHZ} , t_{PLZ}	SEL	A or B	1		8.5	ns
$t_{sk(o)}$ ⁽³⁾	A or B	B or A		0.1	0.2	ns
$t_{sk(p)}$ ⁽⁴⁾				0.1	0.2	ns

- (1) All typical values are at $V_{DD} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.
(2) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).
(3) Output skew between center port (A_4 to A_5) to any other port
(4) Skew between opposite transitions of the same output in a given device $|t_{PHL} - t_{PLH}|$

Dynamic Characteristics

over recommended operating free-air temperature range $V_{DD} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TYP ⁽¹⁾	UNIT
X_{TALK}	$R_L = 100 \Omega$, $f = 250 \text{ MHz}$, See Figure 7	-41	dB
O_{IRR}	$R_L = 100 \Omega$, $f = 250 \text{ MHz}$, See Figure 8	-39	dB
BW	See Figure 6	900	MHz

- (1) All typical values are at $V_{DD} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

OPERATING CHARACTERISTICS

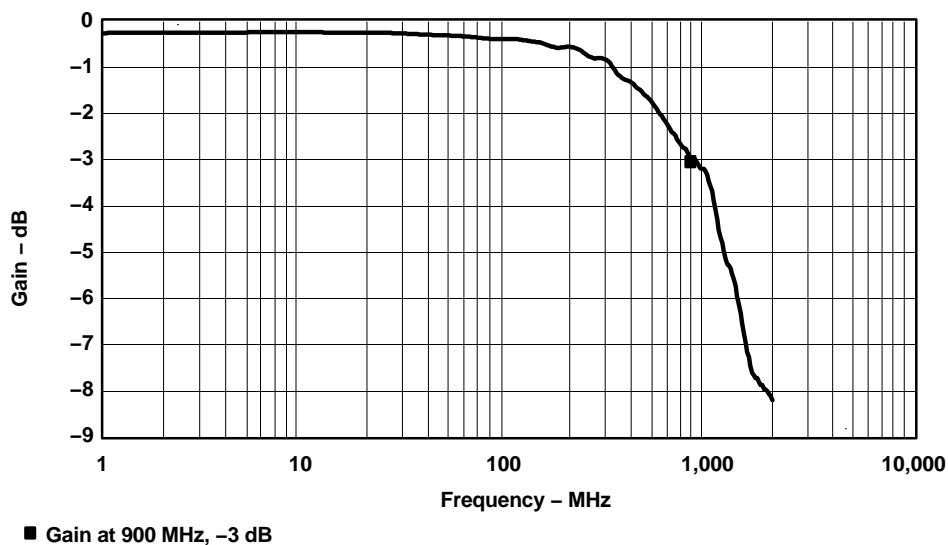


Figure 1. Gain vs Frequency

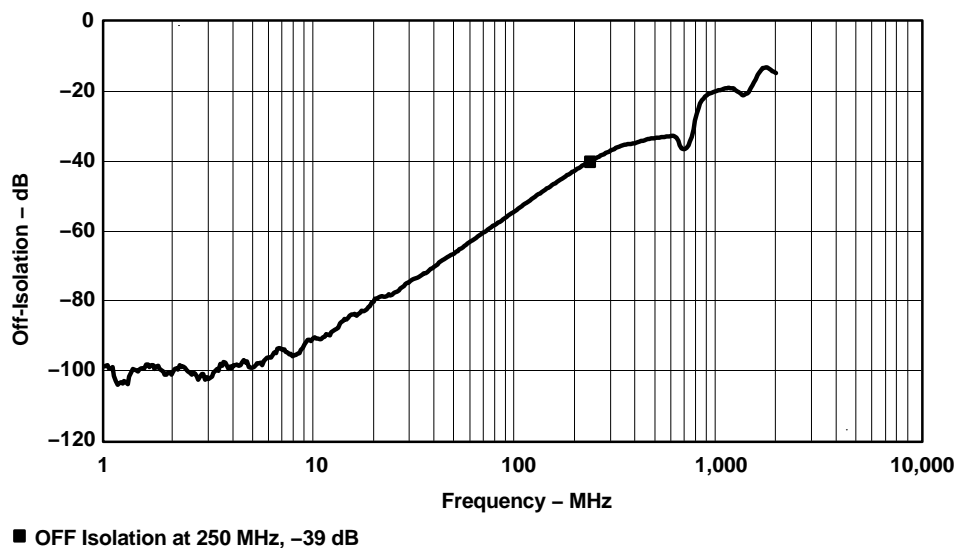


Figure 2. OFF Isolation vs Frequency

OPERATING CHARACTERISTICS

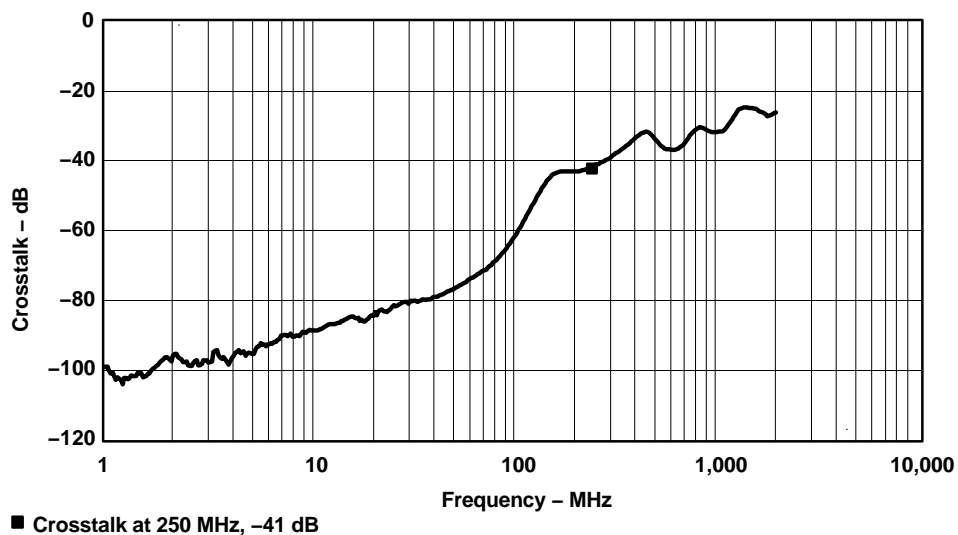


Figure 3. Crosstalk vs Frequency

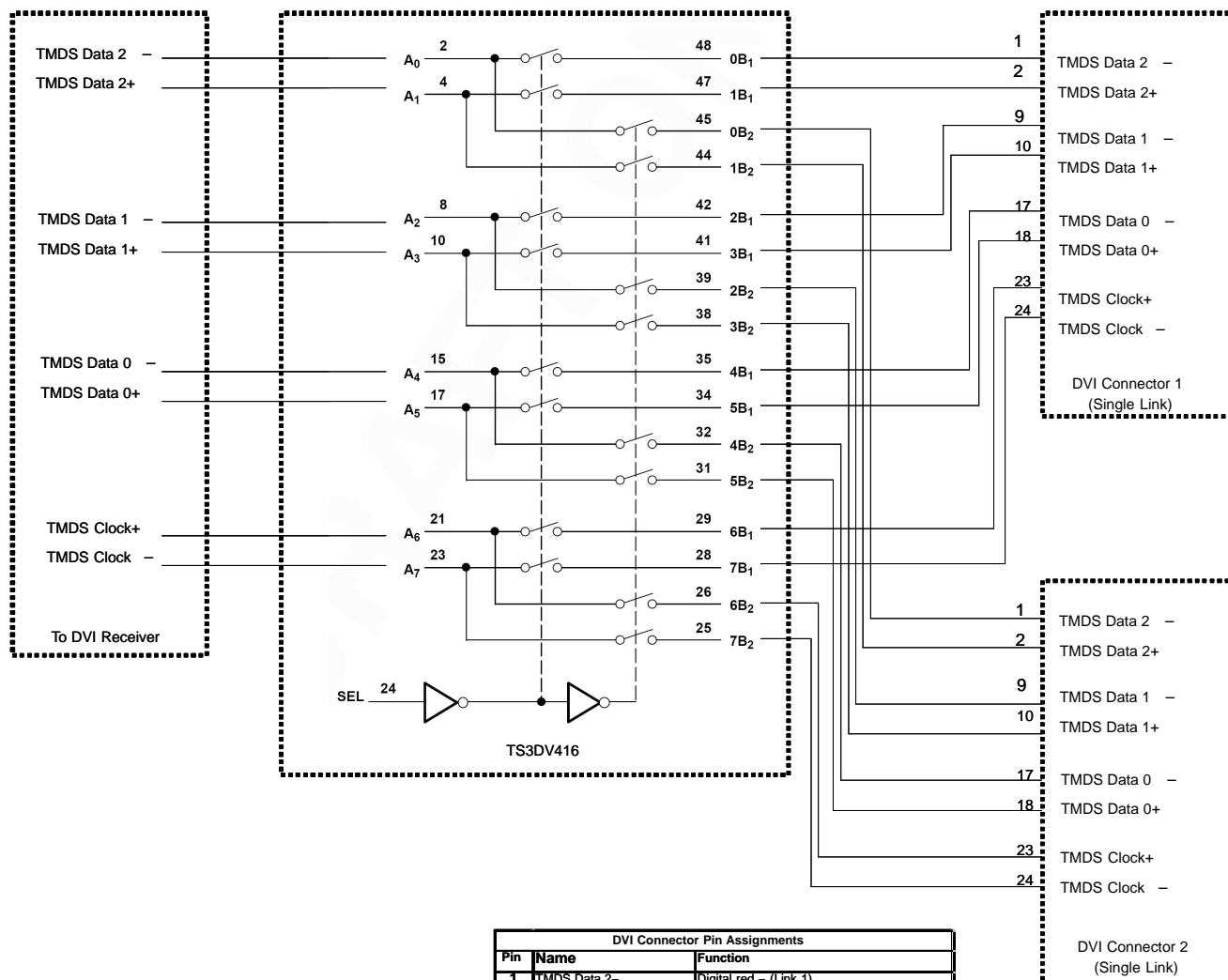
TS3DV416

4-CHANNEL DIFFERENTIAL 8:16 MUX SWITCH

FOR DVI/HDMI APPLICATIONS

SCDS198–OCTOBER 2005

APPLICATION INFORMATION



Typical DVI Connector

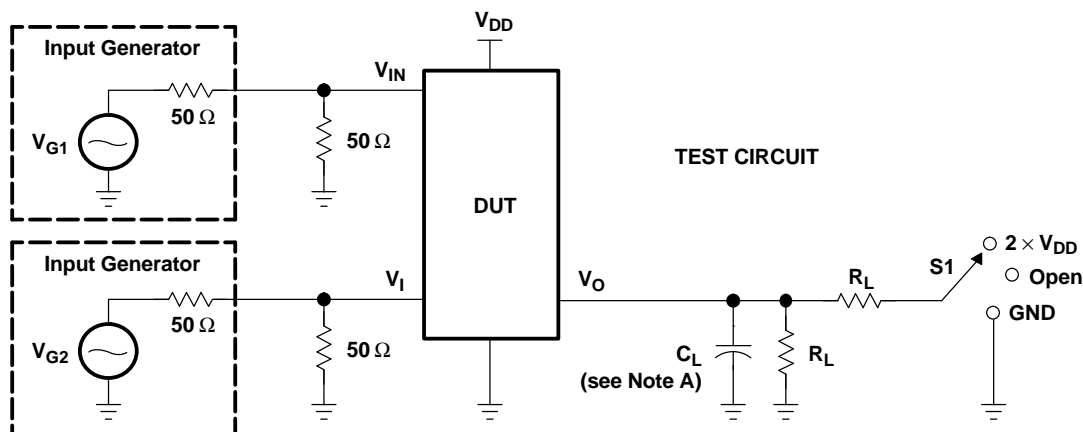


1	2	3	4	5	6	7	8	C1	C2
9	10	11	12	13	14	15	16	C5	
17	18	19	20	21	22	23	24	C3	C4

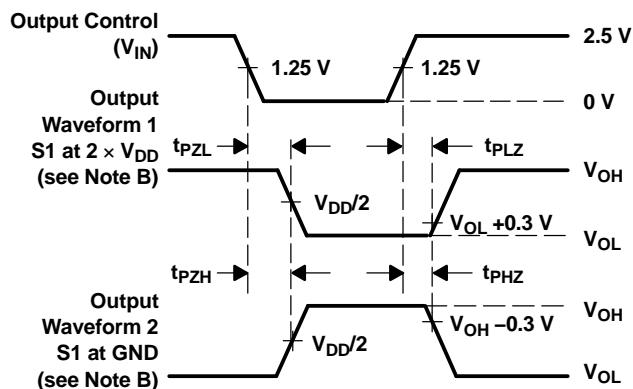
The TS3DV416 can be used to switch between two digital video ports.

DVI Connector Pin Assignments		
Pin	Name	Function
1	TMDS Data 2-	Digital red - (Link 1)
2	TMDS Data 2+	Digital red + (Link 1)
3	TMDS Data 2/4 shield	
4	TMDS Data 4-	Digital green - (Link 2)
5	TMDS Data 4+	Digital green + (Link 2)
6	DDC clock	
7	DDC data	
8	Analog Vertical Sync	
9	TMDS Data 1-	Digital green - (Link 1)
10	TMDS Data 1+	Digital green + (Link 1)
11	TMDS Data 1/3 shield	
12	TMDS Data 3-	Digital blue - (Link 2)
13	TMDS Data 3+	Digital blue + (Link 2)
14	+5V	Power for monitor when in standby
15	Ground	Return for pin 14 and analog sync
16	Hot Plug Detect	
17	TMDS data 0-	Digital blue - (Link 1) and digital sync
18	TMDS data 0+	Digital blue + (Link 1) and digital sync
19	TMDS data 0/5 shield	
20	TMDS data 5-	Digital red - (Link 2)
21	TMDS data 5+	Digital red + (Link 2)
22	TMDS clock shield	
23	TMDS clock+	Digital clock + (Links 1 and 2)
24	TMDS clock-	Digital clock - (Links 1 and 2)
C1	Analog Red	
C2	Analog Green	
C3	Analog Blue	
C4	Analog Horizontal Sync	
C5	Analog Ground	Return for R, G and B signals

PARAMETER MEASUREMENT INFORMATION (Enable and Disable Times)



TEST	V _{DD}	S1	R _L	V _I	C _L	V _Δ
t _{PLZ} /t _{PZL}	3.3 V ± 0.3 V	2 × V _{DD}	200 Ω	GND	10 pF	0.3 V
t _{PHZ} /t _{PZH}	3.3 V ± 0.3 V	GND	200 Ω	V _{DD}	10 pF	0.3 V

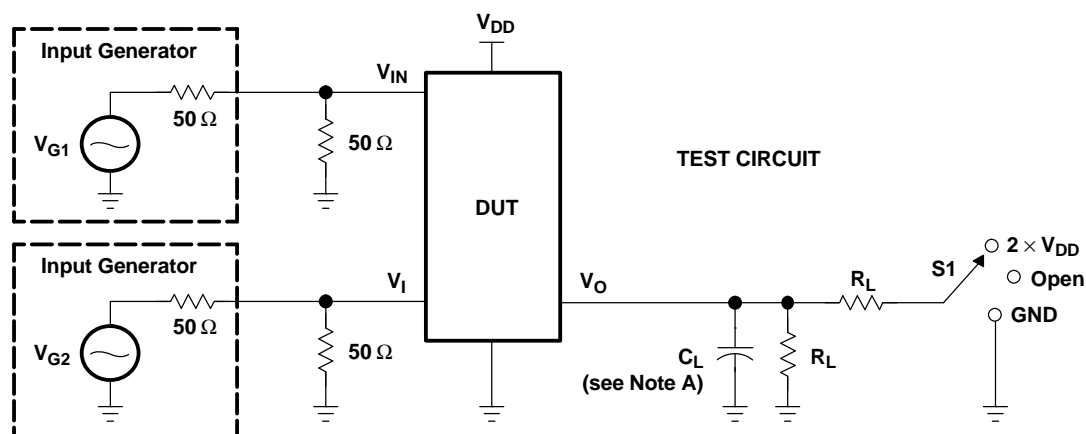


VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

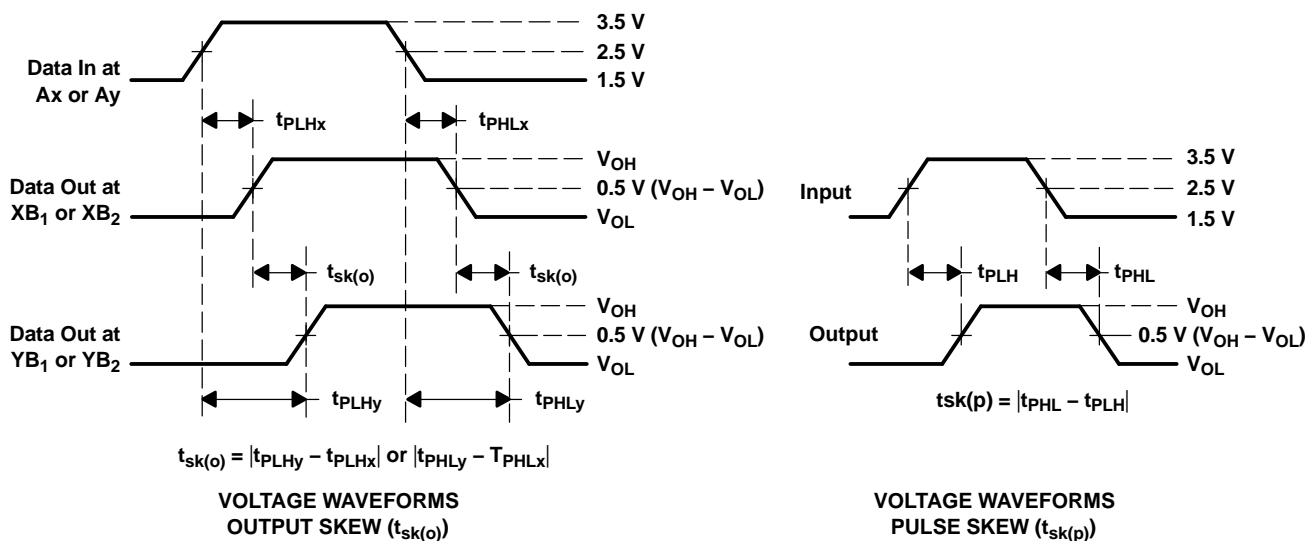
- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.

Figure 4. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (Skew)



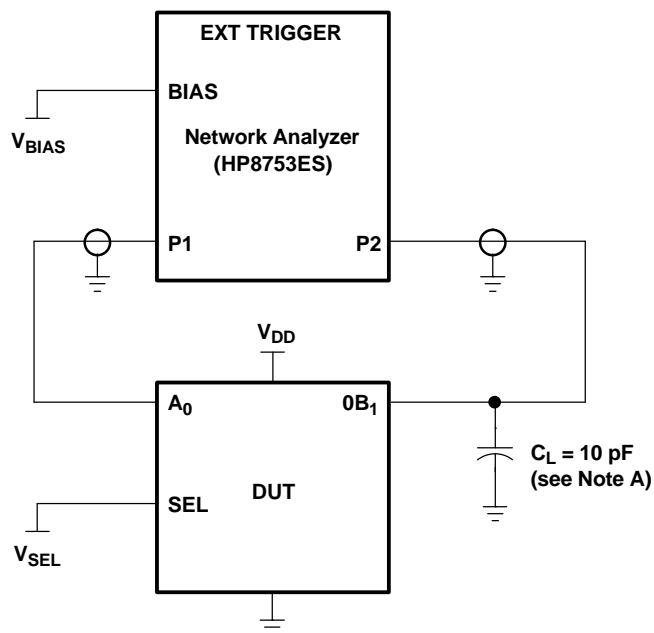
TEST	V _{DD}	S1	R _L	V _I	C _L	V _Δ
t _{sk(o)}	3.3 V ± 0.3 V	Open	200 Ω	V _{DD} or GND	10 pF	
t _{sk(p)}	3.3 V ± 0.3 V	Open	200 Ω	V _{DD} or GND	10 pF	



- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O = 50\ \Omega$, $t_r \leq 2.5\ ns$, $t_f \leq 2.5\ ns$.
D. The outputs are measured one at a time, with one transition per measurement.

Figure 5. Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTE A: C_L includes probe and jig capacitance.

Figure 6. Test Circuit for Frequency Response (BW)

Frequency response is measured at the output of the ON channel. For example, when $V_{SEL} = 0$ and A_0 is the input, the output is measured at $0B_1$. All unused analog I/O ports are left open.

HP8753ES Setup

Average = 4

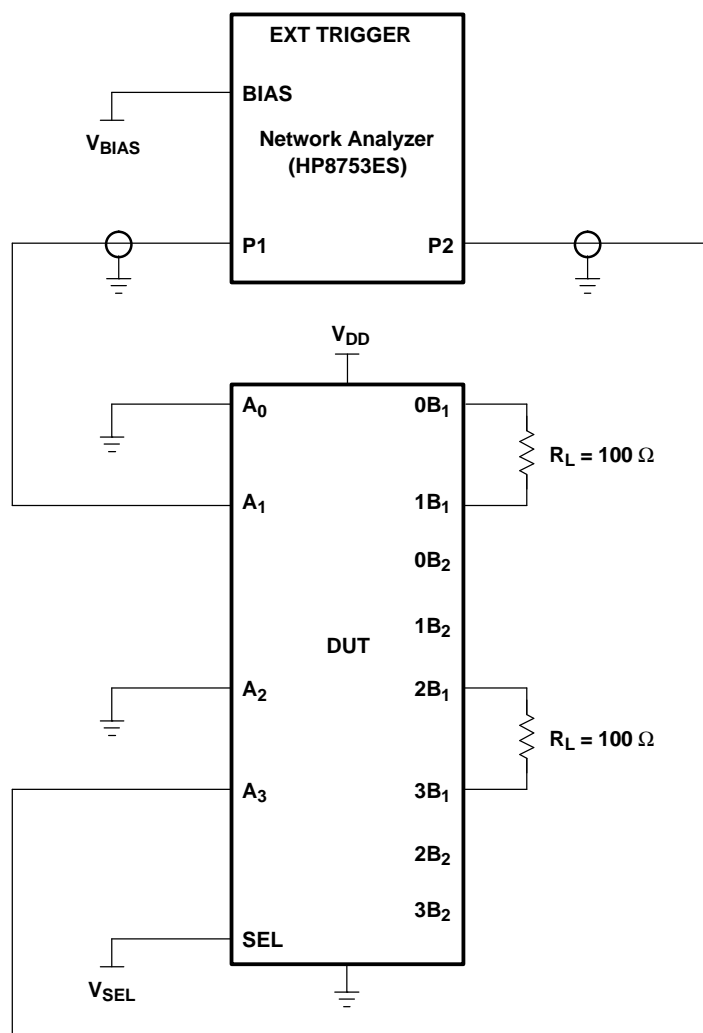
RBW = 3 kHz

$V_{BIAS} = 0.35$ V

ST = 2 s

P1 = 0 dBm

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
B. A 50- Ω termination resistor is needed to match the loading of the network analyzer.

Figure 7. Test Circuit for Crosstalk (X_{TALK})

Crosstalk is measured at the output of the nonadjacent ON channel. For example, when $V_{SEL} = 0$ and A_1 is the input, the output is measured at A_3 . All unused analog input (A) ports are connected to GND, and output (B) ports are left open.

HP8753ES Setup

Average = 4

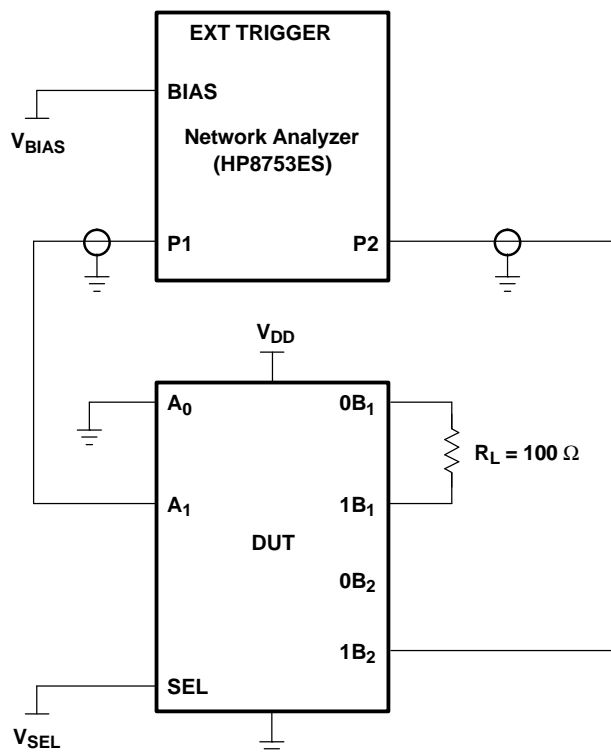
RBW = 3 kHz

$V_{BIAS} = 0.35$ V

ST = 2 s

P1 = 0 dBm

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
B. A 50- Ω termination resistor is needed to match the loading of the network analyzer.

Figure 8. Test Circuit for OFF Isolation (O_{IRR})

OFF isolation is measured at the output of the OFF channel. For example, when $V_{SEL} = GND$ and A_1 is the input, the output is measured at $1B_2$. All unused analog input (A) ports are connected to ground, and output (B) ports are left open.

HP8753ES Setup

Average = 4

RBW = 3 kHz

$V_{BIAS} = 0.35$ V

ST = 2 s

P1 = 0 dBm

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TS3DV416DGGR	ACTIVE	TSSOP	DGG	48		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS3DV416DGGRE4	ACTIVE	TSSOP	DGG	48		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS3DV416DGVR	ACTIVE	TVSOP	DGV	48		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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